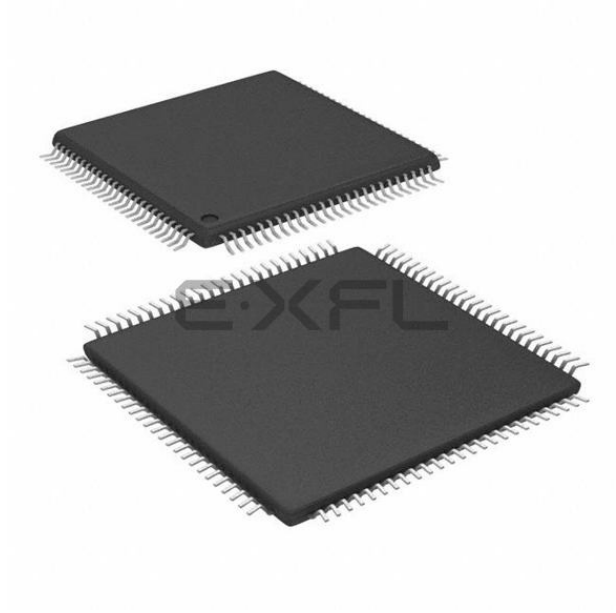
Microchip Technology - PIC24HJ128GP310A-I/PT Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj128gp310a-i-pt

2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to ≤ 8 MHz for start-up with PLL enabled to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the A/D input pins (ANx) as “digital” pins, by setting all bits in the AD1PCFGL register.

The bits in this register that correspond to the A/D pins that are initialized by MPLAB ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain A/D pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFGL register during initialization of the ADC module.

When MPLAB ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the AD1PCFGL register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all A/D pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternatively, connect a 1k to 10k resistor between VSS and the unused pins.

TABLE 4-17: DMA REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DMA0CON	0380	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA0REQ	0382	FORCE	—	—	—	—	—	—	—	—	IRQSEL<6:0>							0000
DMA0STA	0384	STA<15:0>																0000
DMA0STB	0386	STB<15:0>																0000
DMA0PAD	0388	PAD<15:0>																0000
DMA0CNT	038A	—	—	—	—	—	—	CNT<9:0>										0000
DMA1CON	038C	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA1REQ	038E	FORCE	—	—	—	—	—	—	—	—	IRQSEL<6:0>							0000
DMA1STA	0390	STA<15:0>																0000
DMA1STB	0392	STB<15:0>																0000
DMA1PAD	0394	PAD<15:0>																0000
DMA1CNT	0396	—	—	—	—	—	—	CNT<9:0>										0000
DMA2CON	0398	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA2REQ	039A	FORCE	—	—	—	—	—	—	—	—	IRQSEL<6:0>							0000
DMA2STA	039C	STA<15:0>																0000
DMA2STB	039E	STB<15:0>																0000
DMA2PAD	03A0	PAD<15:0>																0000
DMA2CNT	03A2	—	—	—	—	—	—	CNT<9:0>										0000
DMA3CON	03A4	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA3REQ	03A6	FORCE	—	—	—	—	—	—	—	—	IRQSEL<6:0>							0000
DMA3STA	03A8	STA<15:0>																0000
DMA3STB	03AA	STB<15:0>																0000
DMA3PAD	03AC	PAD<15:0>																0000
DMA3CNT	03AE	—	—	—	—	—	—	CNT<9:0>										0000
DMA4CON	03B0	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA4REQ	03B2	FORCE	—	—	—	—	—	—	—	—	IRQSEL<6:0>							0000
DMA4STA	03B4	STA<15:0>																0000
DMA4STB	03B6	STB<15:0>																0000
DMA4PAD	03B8	PAD<15:0>																0000
DMA4CNT	03BA	—	—	—	—	—	—	CNT<9:0>										0000
DMA5CON	03BC	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA5REQ	03BE	FORCE	—	—	—	—	—	—	—	—	IRQSEL<6:0>							0000
DMA5STA	03C0	STA<15:0>																0000
DMA5STB	03C2	STB<15:0>																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

4.4.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program space without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit, word wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.

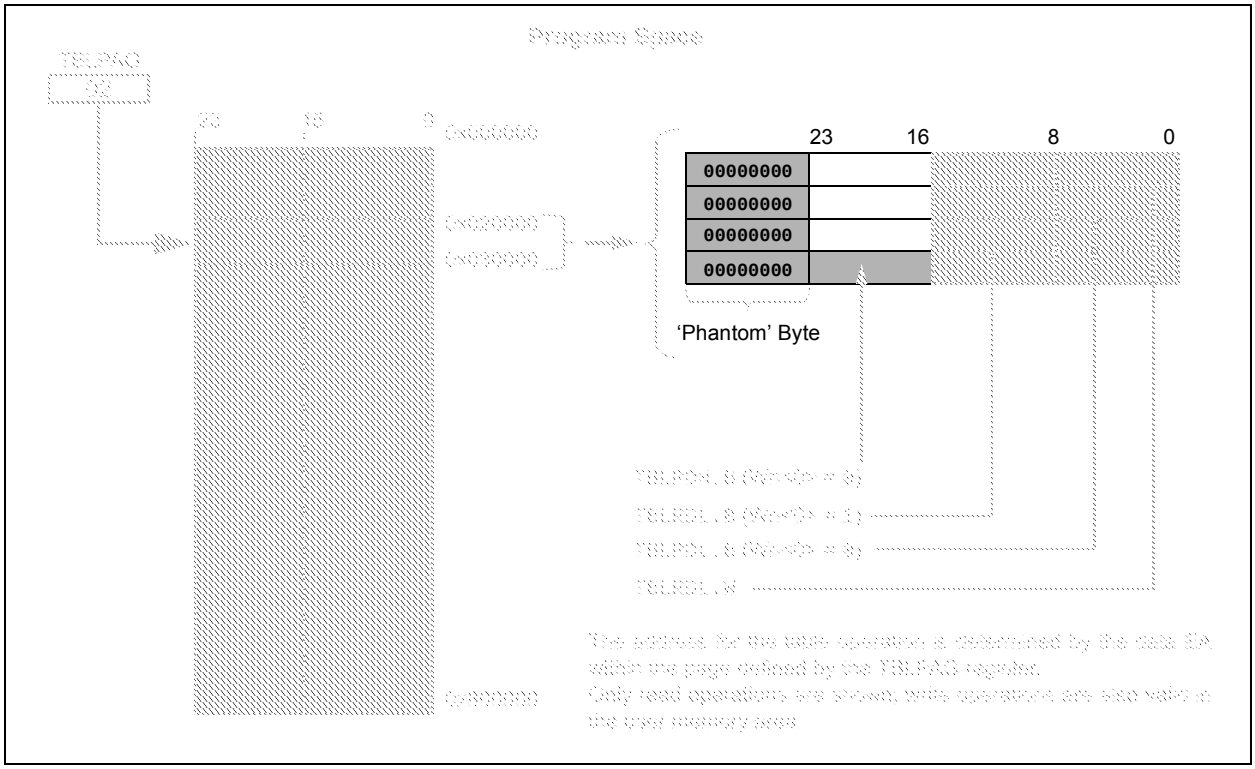
2. TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom byte', will always be '0'.

   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-7: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



REGISTER 7-6: IFS1: INTERRUPT FLAG STATUS REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA21IF
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
IC8IF	IC7IF	AD2IF	INT1IF	CNIF	—	MI2C1IF	SI2C1IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **U2TXIF:** UART2 Transmitter Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 14 **U2RXIF:** UART2 Receiver Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 13 **INT2IF:** External Interrupt 2 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12 **T5IF:** Timer5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **T4IF:** Timer4 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10 **OC4IF:** Output Compare Channel 4 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 9 **OC3IF:** Output Compare Channel 3 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 8 **DMA21IF:** DMA Channel 2 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7 **IC8IF:** Input Capture Channel 8 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **IC7IF:** Input Capture Channel 7 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **AD2IF:** ADC2 Conversion Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **INT1IF:** External Interrupt 1 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 7-9: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
C2TXIF	C1TXIF	DMA7IF	DMA6IF	—	U2EIF	U1EIF	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **C2TXIF:** ECAN2 Transmit Data Request Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **C1TXIF:** ECAN1 Transmit Data Request Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **DMA7IF:** DMA Channel 7 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **DMA6IF:** DMA Channel 6 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **Unimplemented:** Read as '0'

bit 2 **U2EIF:** UART2 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **U1EIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **Unimplemented:** Read as '0'

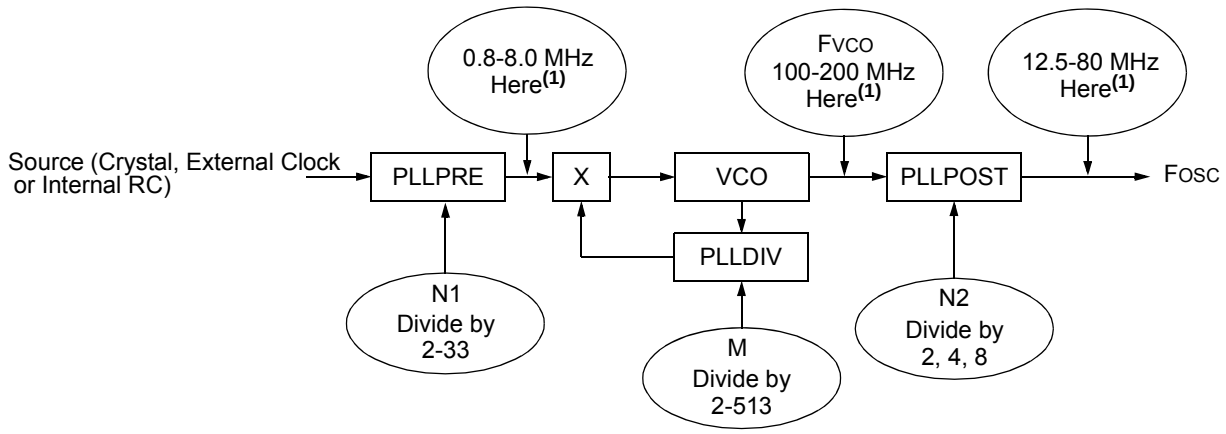
For example, suppose a 10 MHz crystal is being used, with “XT with PLL” being the selected oscillator mode. If PLLPRE<4:0> = 0, then N1 = 2. This yields a VCO input of 10/2 = 5 MHz, which is within the acceptable range of 0.8-8 MHz. If PLLDIV<8:0> = 0x1E, then M = 32. This yields a VCO output of 5 x 32 = 160 MHz, which is within the 100-200 MHz ranged needed.

If PLLPOST<1:0> = 0, then N2 = 2. This provides a Fosc of 160/2 = 80 MHz. The resultant device operating speed is 80/2 = 40 MIPS.

EQUATION 9-3: XT WITH PLL MODE EXAMPLE

$$F_{CY} = \frac{F_{OSC}}{2} = \frac{1}{2}\left(\frac{10000000 \cdot 32}{2 \cdot 2}\right) = 40 \text{ MIPS}$$

FIGURE 9-2: PIC24HJXXXGPX06A/X08A/X10A PLL BLOCK DIAGRAM



Note 1: This frequency range must be satisfied at all times.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Secondary (Timer1) Oscillator (Sosc)	Secondary	xx	100	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	**—**
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	**—**
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	**—**
Primary Oscillator (XT)	Primary	01	010	**—**
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

NOTES:

REGISTER 10-2: PMD2: PERIPHERAL MODULE DISABLE CONTROL REGISTER 2 (CONTINUED)

bit 3 **OC4MD:** Output Compare 4 Module Disable bit
1 = Output Compare 4 module is disabled
0 = Output Compare 4 module is enabled

bit 2 **OC3MD:** Output Compare 3 Module Disable bit
1 = Output Compare 3 module is disabled
0 = Output Compare 3 module is enabled

bit 1 **OC2MD:** Output Compare 2 Module Disable bit
1 = Output Compare 2 module is disabled
0 = Output Compare 2 module is enabled

bit 0 **OC1MD:** Output Compare 1 Module Disable bit
1 = Output Compare 1 module is disabled
0 = Output Compare 1 module is enabled

REGISTER 16-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)(2)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
•
•
•
000 = Secondary prescale 8:1

bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)(2)
11 = Primary prescale 1:1
10 = Primary prescale 4:1
01 = Primary prescale 16:1
00 = Primary prescale 64:1

Note 1: The CKE bit is not used in the Framed SPI modes. The user should program this bit to '0' for the Framed SPI modes (FRMEN = 1).

2: Do not set both Primary and Secondary prescalers to a value of 1:1.

3: This bit must be cleared when FRMEN = 1.

REGISTER 17-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^2C master, applicable during master receive)
Value that will be transmitted when the software initiates an Acknowledge sequence.
1 = Send NACK during Acknowledge
0 = Send ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I^2C master, applicable during master receive)
1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence.
0 = Acknowledge sequence not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^2C master)
1 = Enables Receive mode for I^2C. Hardware clear at end of eighth bit of master receive data byte.
0 = Receive sequence not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^2C master)
1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence.
0 = Stop condition not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^2C master)
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence.
0 = Repeated Start condition not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^2C master)
1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence.
0 = Start condition not in progress

REGISTER 20-3: ADxCON3: ADCx CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC<4:0>(1)				
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** ADC Conversion Clock Source bit
1 = ADC internal RC clock
0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** Analog-to-Digital Conversion Clock Select bits(2)
11111111 = Reserved
•
•
•
01000000 = Reserved
00111111 = TCY · (ADCS<7:0> + 1) = 64 · TCY = TAD
•
•
•
00000010 = TCY · (ADCS<7:0> + 1) = 3 · TCY = TAD
00000001 = TCY · (ADCS<7:0> + 1) = 2 · TCY = TAD
00000000 = TCY · (ADCS<7:0> + 1) = 1 · TCY = TAD

Note 1: This bit only used if ADxCON1<7:5> (SSRC<2:0>) = 111.
2: This bit is not used if ADxCON3<15> (ADRC) = 1.

TABLE 21-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Register	RTSP Effect	Description
BWRP	FBS	Immediate	Boot Segment Program Flash Write Protection 1 = Boot segment may be written 0 = Boot segment is write-protected
BSS<2:0>	FBS	Immediate	Boot Segment Program Flash Code Protection Size X11 = No Boot program Flash segment Boot space is 1K IW less VS 110 = Standard security; boot program Flash segment starts at End of VS, ends at 0x0007FE 010 = High security; boot program Flash segment starts at End of VS, ends at 0x0007FE Boot space is 4K IW less VS 101 = Standard security; boot program Flash segment starts at End of VS, ends at 0x001FFE 001 = High security; boot program Flash segment starts at End of VS, ends at 0x001FFE Boot space is 8K IW less VS 100 = Standard security; boot program Flash segment starts at End of VS, ends at 0x003FFE 000 = High security; boot program Flash segment starts at End of VS, ends at 0x003FFE
RBS<1:0>	FBS	Immediate	Boot Segment RAM Code Protection 11 = No Boot RAM defined 10 = Boot RAM is 128 Bytes 01 = Boot RAM is 256 Bytes 00 = Boot RAM is 1024 Bytes
SWRP	FSS	Immediate	Secure Segment Program Flash Write Protection 1 = Secure segment may be written 0 = Secure segment is write-protected

23.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit™ 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows® programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit™ 2 enables in-circuit debugging on most PIC® microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

23.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

23.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

24.1 DC Characteristics

TABLE 24-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp Range (in °C)	Max MIPS
			PIC24HJXXXGPX06A/X08A/X10A
—	VBOR-3.6V(1)	-40°C to +85°C	40
—	VBOR-3.6V(1)	-40°C to +125°C	40

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 24-11 for the minimum and maximum BOR values.

TABLE 24-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+150	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 24-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 100-pin TQFP (14x14x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 100-pin TQFP (12x12x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 64-pin TQFP (10x10x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 64-pin QFN (9x9x0.9 mm)	θJA	28	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 24-17: PLL CLOCK TIMING SPECIFICATIONS (VDD = 3.0V TO 3.6V)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range(2)	0.8	—	8	MHz	ECPLL, HSPLL, XTPLL modes
OS51	FSYS	On-Chip VCO System Frequency	100	—	200	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	mS	—
OS53	DCLK	CLKO Stability (Jitter)	-3	0.5	3	%	Measured over 100 ms period

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: These parameters are characterized by similarity but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time base or communication clocks used by peripherals use the formula:

Peripheral Clock Jitter = DCLK / √(FOSC/Peripheral bit rate clock)

Example Only: Fosc = 80 MHz, DCLK = 3%, SPI bit rate clock, (i.e. SCK), is 5 MHz

SPI SCK Jitter = [DCLK / √(80 MHz/5 MHz)] = [3%/ √16] = [3% / 4] = 0.75%

TABLE 24-18: AC CHARACTERISTICS: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	Internal FRC Accuracy @ 7.3728 MHz(1)						
F20a	FRC	-2	—	+2	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F20b	FRC	-5	—	+5	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

Note 1: Frequency calibrated at 25°C and 3.3V. TUN bits can be used to compensate for temperature drift.

TABLE 24-19: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	LPRC @ 32.768 kHz(1)						
F21a	LPRC	-30	—	+30	%	-40°C ≤ TA ≤ +85°C	—
F21b	LPRC	-35	—	+35	%	-40°C ≤ TA ≤ +125°C	—

Note 1: Change of LPRC frequency as VDD changes.

25.1 High Temperature DC Characteristics

TABLE 25-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			PIC24HJXXXGPX06A/X08A/X10A
HDC5	VBOR to 3.6V(1)	-40°C to +150°C	20

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 24-11 for the minimum and maximum BOR values.

TABLE 25-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal chip power dissipation: PINT = VDD x (IDD - Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD - VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ - TA)/θJA			W

TABLE 25-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Operating Voltage							
HDC10	**Supply Voltage**						
	VDD	—	3.0	3.3	3.6	V	-40°C to +150°C

TABLE 25-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	Typical	Max	Units	Conditions		
Power-Down Current (IPD)						
HDC60e	250	2000	μA	+150°C	3.3V	Base Power-Down Current(1,3)

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 25-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V See **Note 1**
HDO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
HDO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

TABLE 25-9: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature						
Param No.	Characteristic	Min	Typ	Max	Units	Conditions	
	LPRC @ 32.768 kHz (1)						
HF21	LPRC	-70(2)	—	+70(2)	%	-40°C ≤ TA ≤ +150°C	—

Note 1: Change of LPRC frequency as VDD changes.

2: Characterized but not tested.

TABLE 25-10: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic(1)	Min	Typ	Max	Units	Conditions
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	—
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	—
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 25-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic(1)	Min	Typ	Max	Units	Conditions
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	—
HSP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	35	—	—	ns	—
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	—
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

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